

M.Carulla :: Photon Science Detector Group :: Paul Scherrer Institute

Soft X-ray detection with single photon resolution using LGAD sensors

19-23 June 2023 :: High Precision X-Ray Measurements 2023 :: Frascati :: Italy

* On behalf of Photon Science Detector group and FBK collaboration



Photon science detector group

Photon counting and charge integrating hybrid detectors: (Aldo's talk on Thursday at 12)



Applications

Powder diffraction



C.J. Milne Appl. Sci. 2017, 7(7), 720; https://doi.org/10.3390/app7070720

Hybrid detectors:

Material and process optimized separately 0

Performance:

- 2-40 kframes/s 0
- High dynamic range Ο
- Large area Ο
- High efficiency for **E**_{ph} > **1.2 keV** 0

Operando diffraction



Hocine et al.; Materials today, 2020; https://doi.org/10.1016/j.mattod.2019.10.001



Macromollecular crystallography



Leonarski et al.; Nature methods, 2018; https://doi.org/10.1038/s41592-018-0143-7



Soft X-rays (200 eV – 1.2 keV):

- Energy between K-edges of C and O: polymers, organic electronics, aerosols, and biological materials
- L-edges of 3d transition metals: cuprate, Mott insulators and ferromagnetic and antiferromagnetic materials



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Development of two technologies

In collaboration with Fondazione Bruno Kessler, we developed two optimized technologies for soft X-rays detection

Entrance window technology

- Optimization of the n+
- Passivation of the surface





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Inverse low gain avalanche diode (iLGAD) technology









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Entrance window technology

- Optimization of the n+
- $\circ \quad \text{Passivation of the surface} \\$





- Large electric field to trigger impact ionization
- Multiplication factor depends on absorption depth
- Optimization of the gain layer











Ultra-shallow

\circ Spectrum with two peaks

Standard design:

 At low energies high probability for hole started impact ionization



Optimization gain layer





Ultra-shallow

 \circ Spectrum with two peaks

Standard design:

- At low energies high probability for hole started impact ionization
- At high energies, high probability for electron started impact ionization







• Spectrum with two peaks

Standard design:

- At low energies high
 probability for hole started
 impact ionization.
- At high energies, high
 probability for electron
 started impact ionization.

Ultra-shallow design:

 At low energies the probability for electron started impact ionization is larger







Spectrum with two peaks

Standard design:

- At low energies high probability for hole started impact ionization.
- At high energies, high probability for electron started impact ionization.

Ultra-shallow design:

- At low energies the probability for hole started impact ionization is larger
- Design with high electric field in small region
- Difference between M_h and
 M_e is smaller.

PAUL SCHERRER INSTITUT Efficiency of the entrance window technology

Quantum efficiency 100 Calibrated 250 eV Readout photodiode board 80 soft X-rays 60 QE [%] beam OSA 40 Pin hole less than 80 µm 20 Standard X-ray sensor Std. sensor 200 400 600 800 1000 1200 Energy [eV]

Setup at the Surface/Interfaces:Microscopy @ SLS

PAUL SCHERRER INSTITUT Efficiency of the entrance window technology



Setup at the Surface/Interfaces Microscopy @ SLS

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Efficiency of the entrance window technology



Efficiency of the entrance window technology



• Reduction of the passivation layer

QE above 70 % of backside illuminated scientific CMOS* and equal to 80 % of entrance window pnCCD**

*K. Desjardins, et al. 2020, J. Synchrotron Rad. 27, 1577–1589.

** S. Send, et al. 2013, NIMA. 711, 132-142.



Setup at the Surface/Interfaces:Microscopy (SIM) beamline from SLS

• Two designs tested with JUNGFRAU : Standard & ultra-shallow



Front side picture



In comparison to the design without gain, the SNR has increased by a factor of 4 for ultra-shallow and 6 for the standard.





Spectrum of iLGAD sensors

Standard



6 <u>le-3</u> 450eV 500eV 2 sigma cut 5 600eV 700eV 3 sigma cut Counts [a.u] Counts [a.u] 2 2 1 1 200 600 800 1000 200 800 400 400 600 0 Energy [eV] Energy [eV] 60 Slope=0.0441+/-0.0006[1/eV] Slope=0.02726+/-0.00018[1/eV] 25 50 Intercept=-2.3+/-0.4 40 · 20 Intercept=-0.93+/-0.12 SNR-e ∞ SNR-e 15 electrons electrons 20 10 10 holes 700 900 1000 400 600 700 200 400 500 600 800 200 300 500 800 300 Energy [eV] Energy [eV]

Ultra-shallow design show Ο low SNR due to the low gain in comparison to standard design

390eV

450eV

500eV

600eV

700eV

1000

holes

900

1000

- Probability of electron 0 started impact ionization for ultra-shallow design is larger than in standard
- The gain needs to be Ο increased for detection of hole started impact ionization at 400 eV



Can we obtain single photon resolution of soft X-rays with our fast detector system?

Optimization of the entrance window to reduce the losses in the surface and n+





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Optimization of the iLGAD design to increase the gain and the probability of photon absorption after the multiplication layer.



Combining the entrance window technology together with the iLGAD technology, our detector systems can detect 400 eV photons at high frame rates.



Acknowledgement

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Photon Science Detector Group

Back: J. Zhang, A. Mozzanica, T. King, D. Mezza, A. Bergamaschi, J. Heymes; *Middle:* E. Fröjdh, C. Lopez, M. Brückner, C. Ruder, B. Schmitt, K. Moustakas, D. Greiffenberg; *Front:* V. Hinger, D. Thattil, R. Dinapoli, S. Hasanaj, M. Carulla, S. Ebner; Missing: R. Barten, P. Kozlowski, F. Baruffaldi, K. Paton and X. Xie









K. Desjardins, et al. 2020, J. Synchrotron Rad. 27, 1577–1589.

- **#** QE > 0.62 current TEW and iLGAD sensors
- **#** QE > 0.8 current prototype







IQE and QE after irradiation

SO saturates to 1e4 cm/s







- ✓ SNR larger than 5
- ✓ Gain independent on the photon absorption depth

X Low fill factor



M. Andra, J. Synchrotron Rad. (2019). 26, 1226–1237 https://doi.org/10.1107/S1600577519005393





Optimization gain layer





ultra-shallow





M.Ferrero et al. "An introduction to Ultra-Fast Silicon Detectors"



Impact ionization



Relationship with electric field and temperature:

$$\alpha_{\nu} = \alpha_{\nu}^{\infty} \cdot exp\left(-\left(\frac{C_{\nu} + D_{\nu}T}{E}\right)^{\beta_{\nu}}\right)$$



D. Massey, "Temperature dependence of impact ionization in submicrometer silicon devices" Page 32

Pure electron started impact ionization

O. Triebl, "Reliability Issues in High-Voltage Semiconductor Devices"